



WANSEMI
万芯半导体

WX015D02D8

Enhancement Mode N+P-Channel Power MOSFET

SOP8/N+PMOS/20V/ ± 12 V/0.65V/6.3A/15m Ω

-20V/ ± 12 V/-0.7V/-8A/28m Ω

Rev0.1

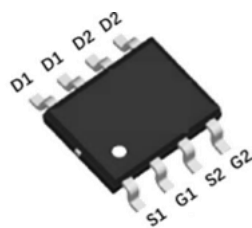
20V N+P-Channel MOSFET

1.Features

- ◆ High power and current handling capability
- ◆ Lead free product is acquired
- ◆ Fast switching
- ◆ Surface mount package
- ◆ 100% UIS Tested

2.Applications

- ◆ Power Switching Application
- ◆ Load Switching



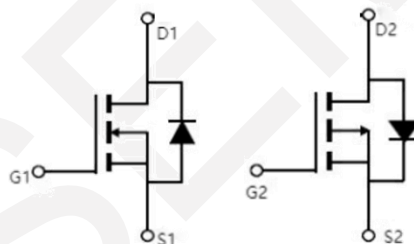
SOP8
Pin Description

◆ N-Channel

V_{DS}	$R_{DS(on)}$ Typ.	I_D
20V	15mΩ @ 4.5V	6.3A
	20mΩ @ 2.5V	

◆ P-Channel

V_{DS}	$R_{DS(on)}$ Typ.	I_D
-20V	28mΩ @ -4.5V	-8A
	35mΩ @ -2.5V	



N-Channel P-Channel

Schematic Diagram

3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WX015D02D8	015D02	SOP8	4,000	48,000

4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter		Symbol	N-channel	P-channel	Units
Drain to Source Voltage		V_{DSS}	20	-20	V
Gate to Source Voltage		V_{GSS}	±12	±12	V
Drain Current (DC)	TA=25 °C	I_D	6.3	-8	A
Drain Current (Pulse), PW≤300μs		I_{DM}	25.2	-32	A
Avalanche Energy, Single Pulsed		E_{AS}	85	78	mJ
Total Dissipation	TA=25 °C	P_D	3.5	3.5	W
Junction Temperature		T_j	150	150	°C
Storage Temperature		T_{stg}	-55 to +150	-55 to +150	°C

Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

5. Thermal Resistance Ratings (Note 2)

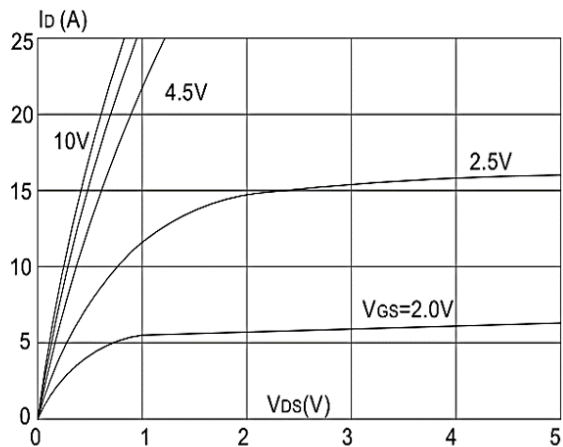
Parameter	Symbol	N-channel	P-channel	Unit
Maximum Junction-to-Ambient	$R_{\theta JA}$	85	85	$^{\circ}\text{C/W}$

Note 2: When mounted on 1 inch square copper board $t \leq 10\text{sec}$ The value in any given application depends on the user's specific board design.

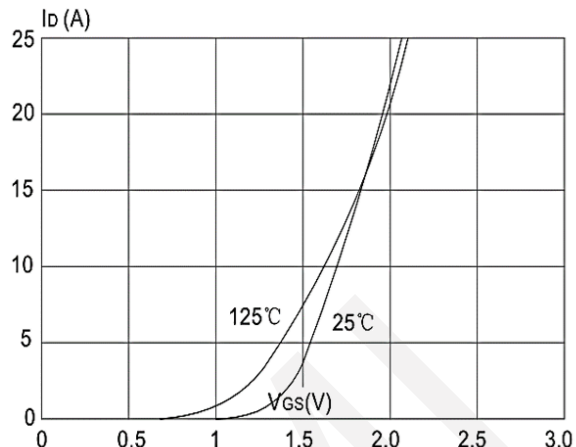
6. NMOS Electrical Characteristics at $T_a=25^{\circ}\text{C}$ (Note 3)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$	20	-	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 20\text{V}$, $V_{GS} = 0\text{V}$	-	-	1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 12\text{V}$, $V_{DS} = 0\text{V}$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}$, $I_{DS}=250\mu\text{A}$	0.5	0.65	1.0	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 4\text{A}$, $V_{GS} = 4.5\text{V}$	-	15	20	$\text{m}\Omega$
		$I_D = 3\text{A}$, $V_{GS} = 2.5\text{V}$	-	20	35	$\text{m}\Omega$
Input Capacitance	C_{iss}	$V_{GS}=0\text{V}$, $V_{DS}=10\text{V}$, Frequency=1.0MHz	-	888	-	pF
Output Capacitance	C_{oss}		-	133	-	pF
Reverse Transfer Capacitance	C_{rss}		-	117	-	pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DS} = 10\text{V}$, $V_{GS} = 4.5\text{V}$, $R_{REN} = 3\Omega$, $I_D=6.3\text{A}$	-	7	-	ns
Rise Time	t_r		-	46	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	30	-	ns
Fall Time	t_f		-	52	-	ns
Total Gate Charge	Q_g	$V_{DS} = 10\text{V}$, $V_{GS} = 4.5\text{V}$, $I_D = 6.3\text{A}$	-	11.05	-	nC
	Q_{gs}		-	1.73	-	nC
	Q_{gd}		-	3.1	-	nC
Diode Forward Voltage	V_{FSD}	$I_S = 6.3\text{A}$, $V_{GS} = 0\text{V}$	-	-	1.2	V

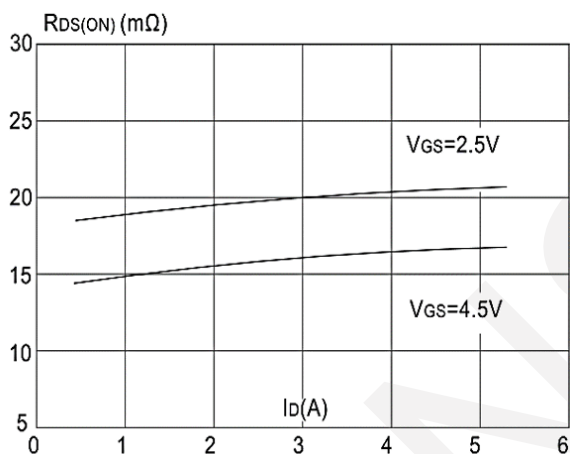
NMOS Typical electrical and thermal characteristics



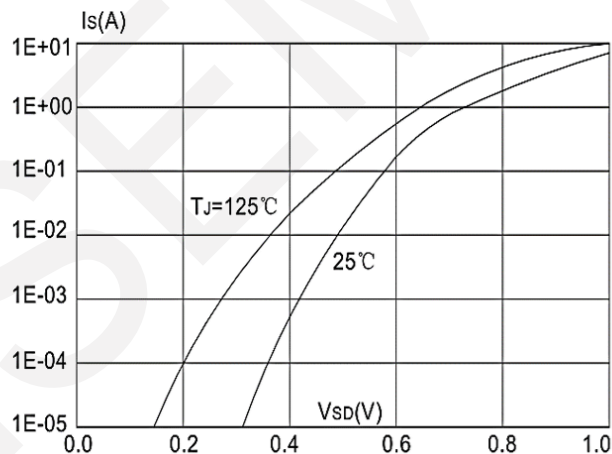
Output Characteristics



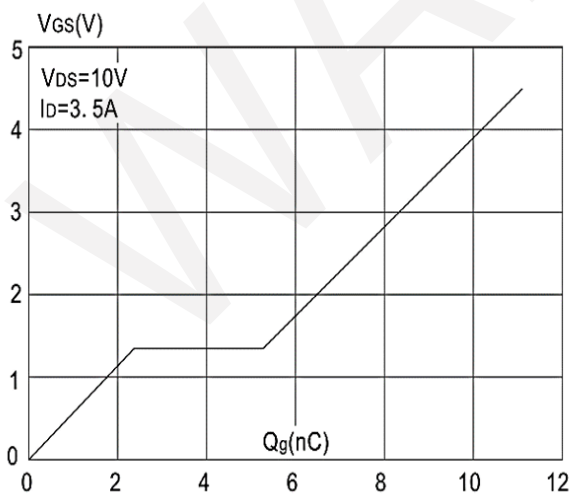
Transfer Characteristics



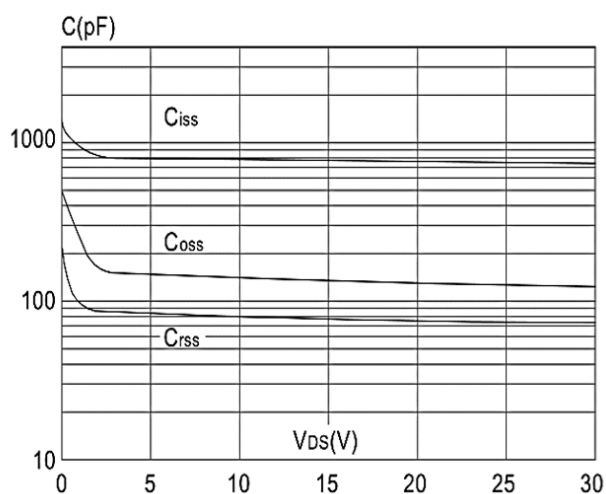
On-resistance vs. Drain Current



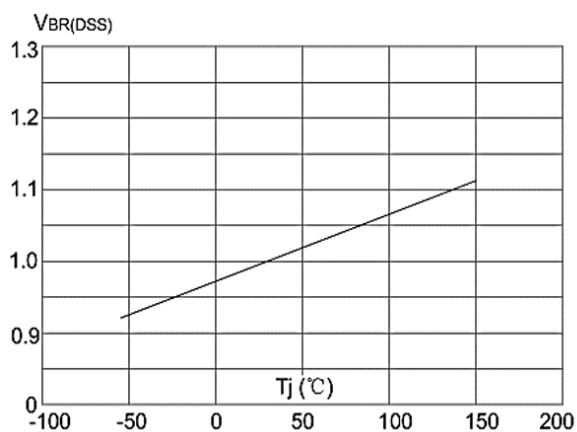
Body Diode Characteristics



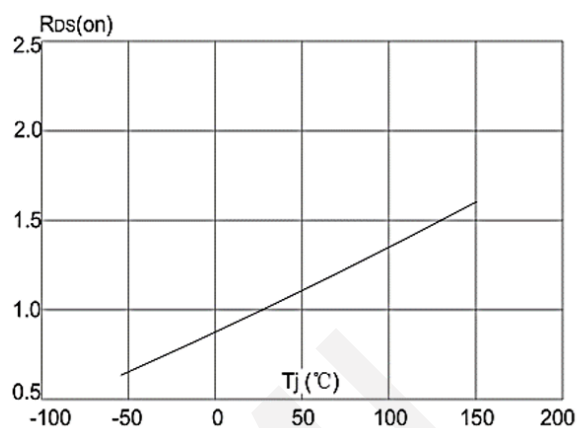
Gate Charge Characteristics



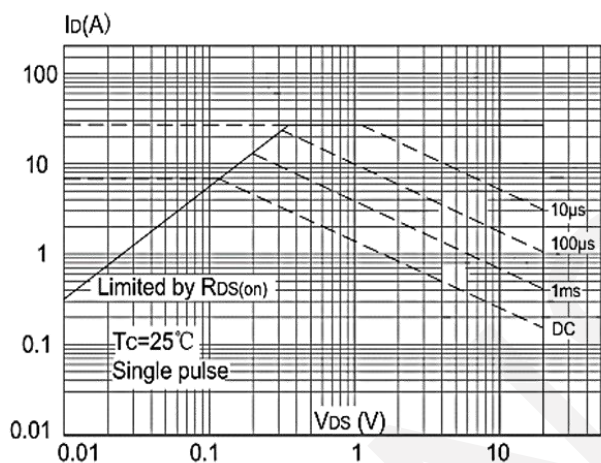
Capacitance Characteristics



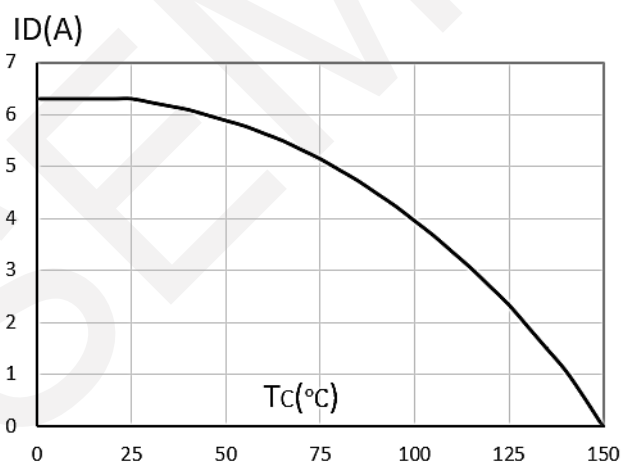
Normalized Breakdown Voltage
vs. Junction Temperature



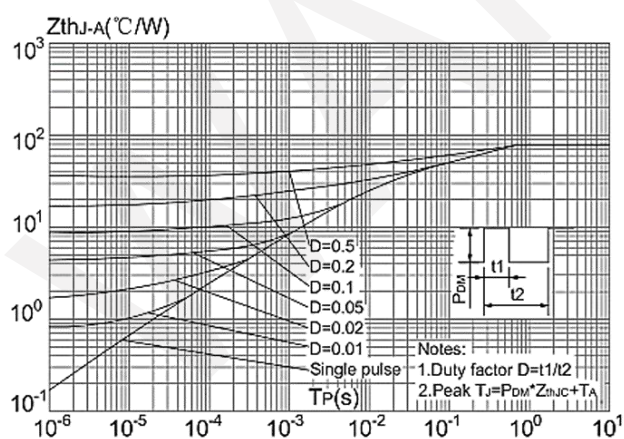
Normalized on Resistance vs.
Junction Temperature



Maximum Safe Operating Area



Maximum Continuous Drain Current vs.
Ambient Temperature

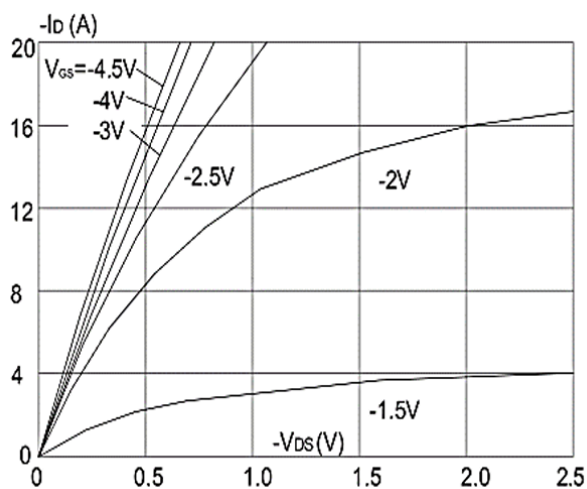
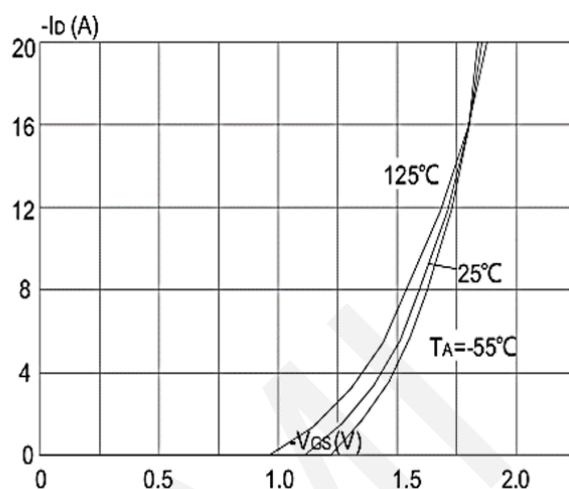
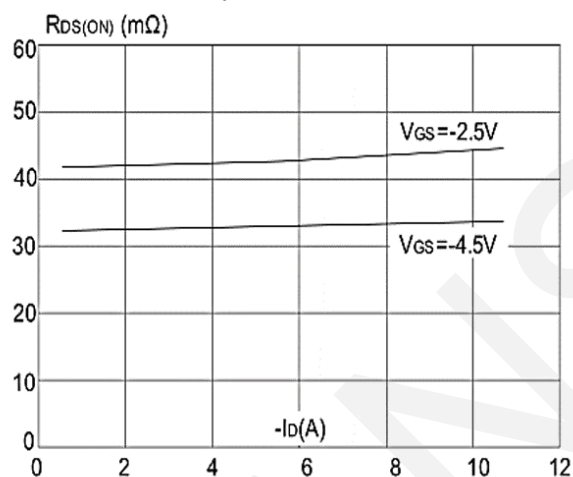
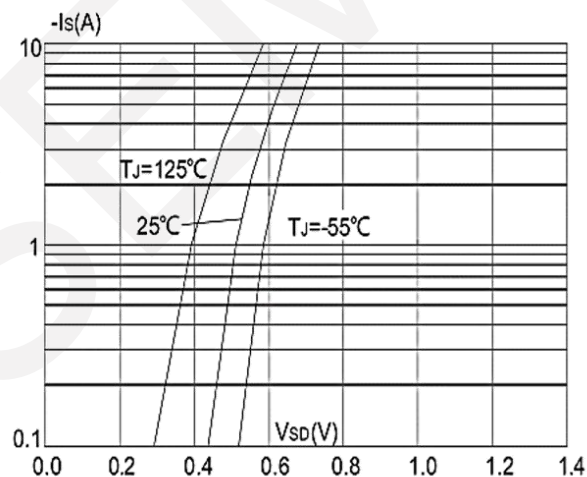
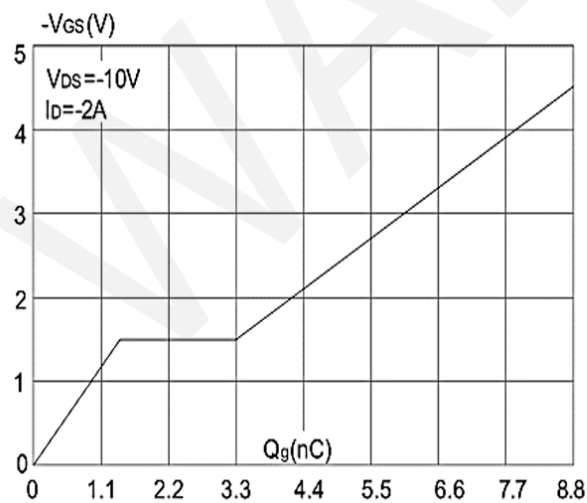
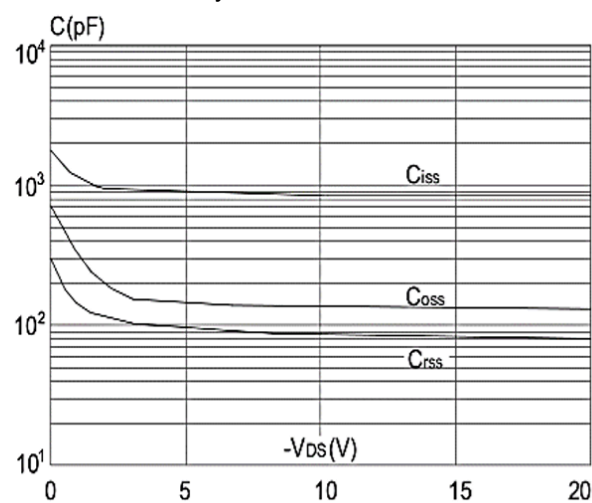


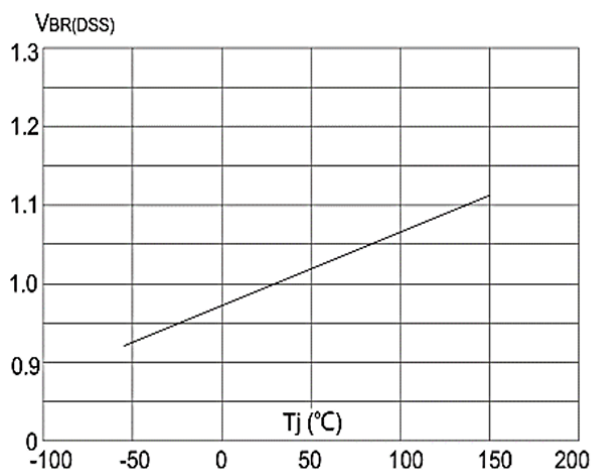
Maximum Effective Transient Thermal
Impedance, Junction-to-Ambient

7. PMOS Electrical Characteristics at Ta=25°C

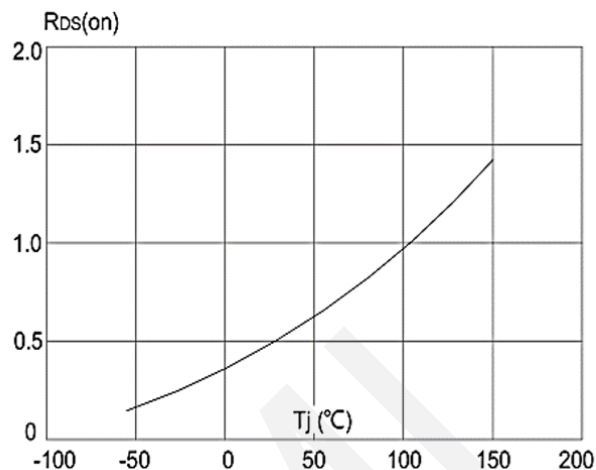
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = -250\mu A, V_{GS} = 0V$	-20	-	-	V
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = -20V, V_{GS} = 0V$	-	-	1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	± 100	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_{DS}=-250\mu A$	-0.5	-0.7	-1.0	V
Static Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = -4A, V_{GS} = -4.5V$	-	28	35	m Ω
		$I_D = -3A, V_{GS} = -2.5V$	-	35	42	m Ω
Input Capacitance	C_{iss}	$V_{GS}=0V,$ $V_{DS}=-10V,$ Frequency=1.0MHz	-	830	-	pF
Output Capacitance	C_{oss}		-	132	-	pF
Reverse Transfer Capacitance	C_{rss}		-	85	-	pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DD} = -10V$ $I_D=-3.3A$ $V_{GS} = -4.5V$ $R_{REN} = 1\Omega$	-	10	-	ns
Rise Time	t_r		-	32	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	50	-	ns
Fall Time	t_f		-	51	-	ns
Total Gate Charge	Q_g	$V_{DS} = -10V,$ $V_{GS} = -4.5V,$ $I_D = -2A$	-	8.8	-	nC
	Q_{gs}		-	1.4	-	nC
	Q_{gd}		-	1.9	-	nC
Diode Forward Voltage	V_{FSD}	$I_S = -4A, V_{GS} = 0V$	-	-	-1.2	V

Note 3: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

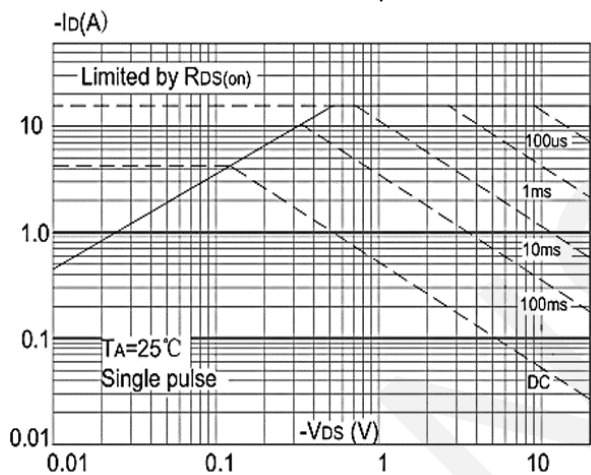
PMOS Typical electrical and thermal characteristics

Output Characteristics

Transfer Characteristics

On-resistance vs. Drain Current

Body Diode Characteristics

Gate Charge Characteristics

Capacitance Characteristics



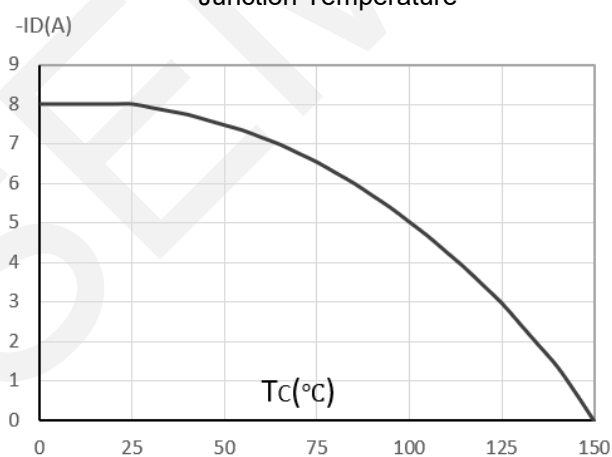
Normalized Breakdown Voltage
vs. Junction Temperature



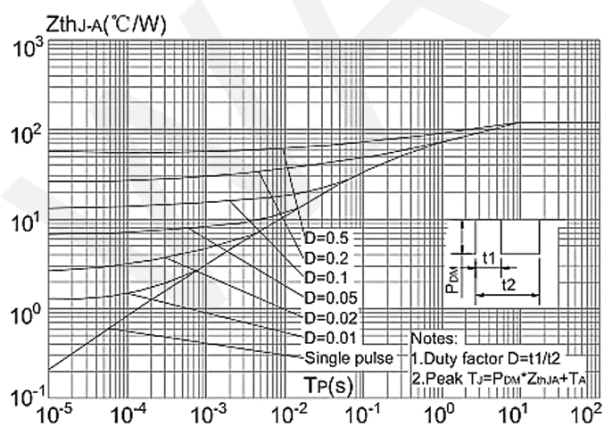
Normalized on Resistance vs.
Junction Temperature



Maximum Safe Operating Area

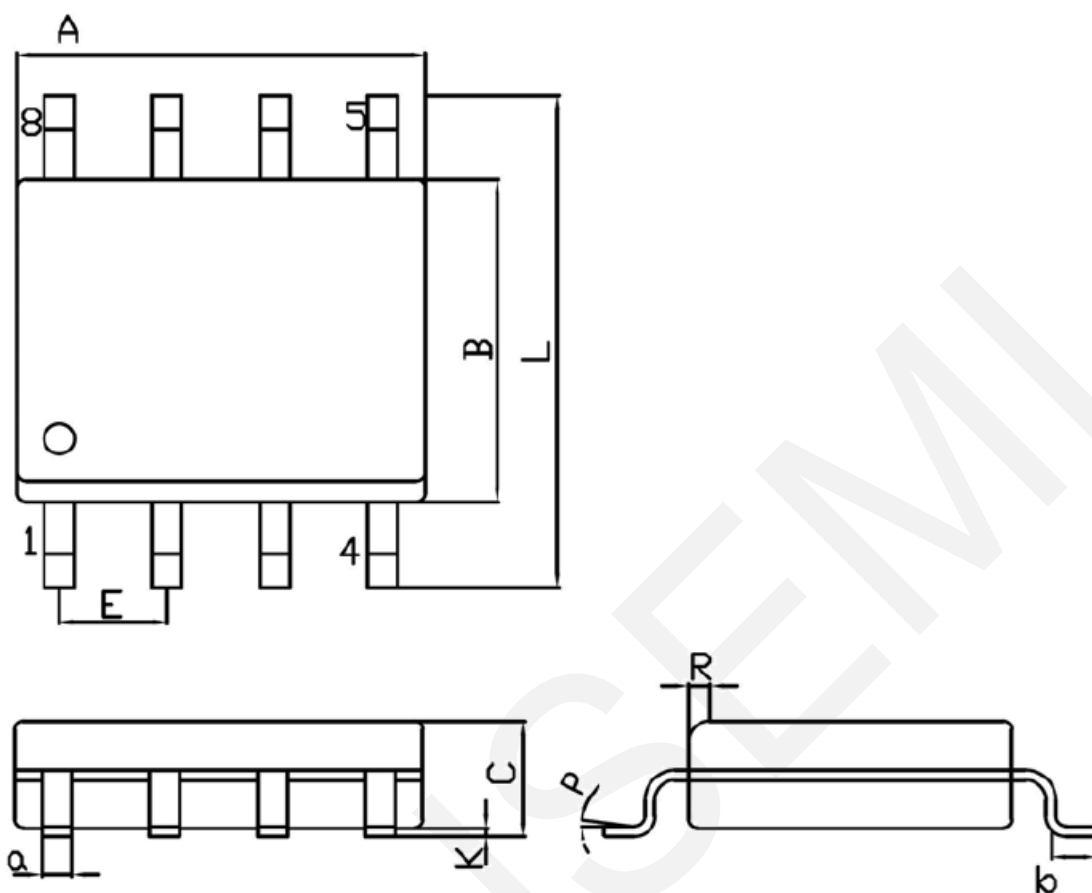


Maximum Continuous Drain Current vs.
Ambient Temperature



Maximum Effective Transient Thermal
Impedance, Junction-to-Ambient

8.Package Dimensions



Symbol	Dimensions In Millimeters		Symbol	Dimensions In Millimeters	
	Min	Max		Min	Max
A	4.70	5.10	C	1.35	1.75
B	3.70	4.10	a	0.35	0.49
L	5.80	6.20	R	0.30	0.60
E	1.27BSC		P	0°	7°
K	0.12	0.22	b	0.40	1.25

9. Important Notice

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